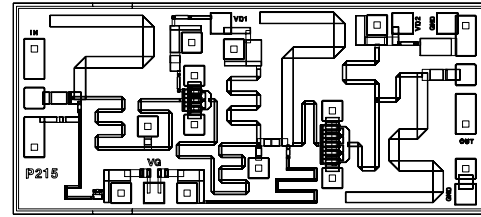


FEATURES

- 12.5 – 16.5 GHz Operating Frequency Range
- 24.0dBm Output Power at 1dB Compression
- 17.0 dB Typical Small Signal Gain
- -40dBc OIMD3 @Each Tone Pout 14dBm

APPLICATIONS

- Point-to-point and point-to-multipoint radio
- Military Radar Systems



Dimension: 2250um X 1000um
Thickness: 75um ± 13um



Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (T_a = 25 °C, 50 ohm, VDD=7V, IDQ=190mA)

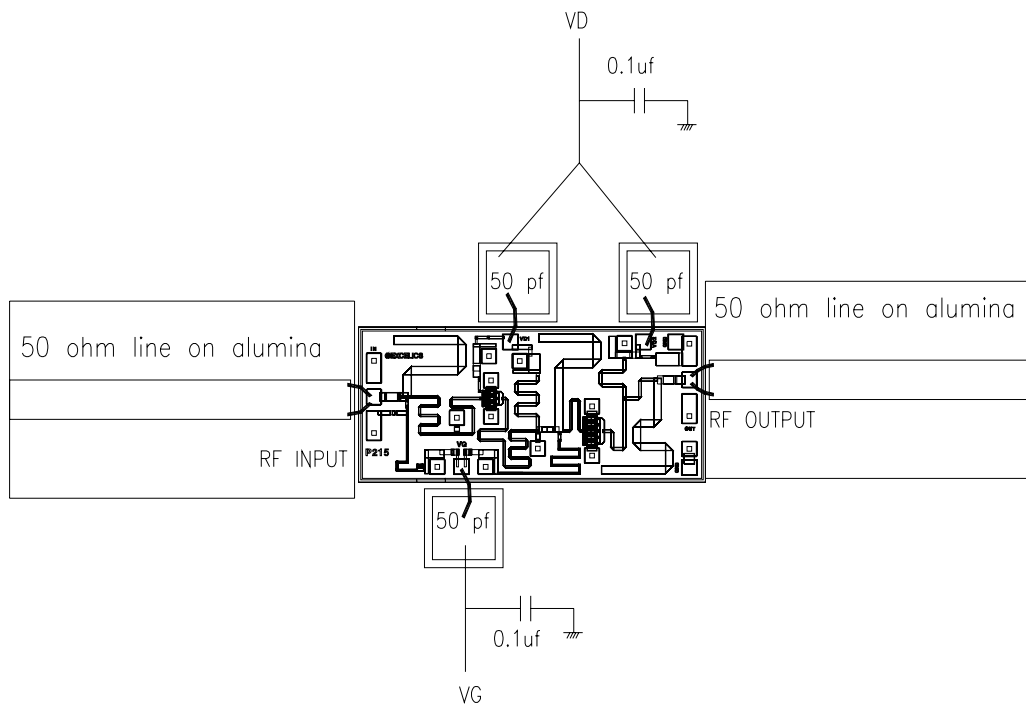
SYMBOL	PARAMETER/TEST CONDITIONS	MIN	TYP	MAX	UNITS
F	Operating Frequency Range	12.5		16.5	GHz
P1dB	Output Power at 1dB Gain Compression	22.5	24.0		dBm
G _{ss}	Small Signal Gain	15.0	17.0		dB
OIMD3	Output 3 rd Order Intermodulation Distortion @Δf=10MHz, Each Tone Pout 14dBm		-40	-37	dBc
Input RL	Input Return Loss		-10	-6	dB
Output RL	Output Return Loss		-10	-6	dB
I _{dss}	Saturate Drain Current V _{DS} =3V, V _{GS} =0V	211	264	317	mA
V _{DD}	Power Supply Voltage		7	8	V
R _{th}	Thermal Resistance (Au-Sn Eutectic Attach)		34		°C/W
T _b	Operating Base Plate Temperature	-35		+85	°C

ABSOLUTE MAXIMUM RATINGS FOR CONTINUOUS OPERATION^{1,2}

SYMBOL	CHARACTERISTIC	VALUE
V _{DS}	Drain to Source Voltage	8 V
V _{GS}	Gate to Source Voltage	-4 V
I _{DD}	Drain Current	I _{dss}
I _{GSF}	Forward Gate Current	4mA
P _{IN}	Input Power	@ 3dB compression
T _{CH}	Channel Temperature	150°C
T _{STG}	Storage Temperature	-65/150°C
P _T	Total Power Dissipation	3.4W

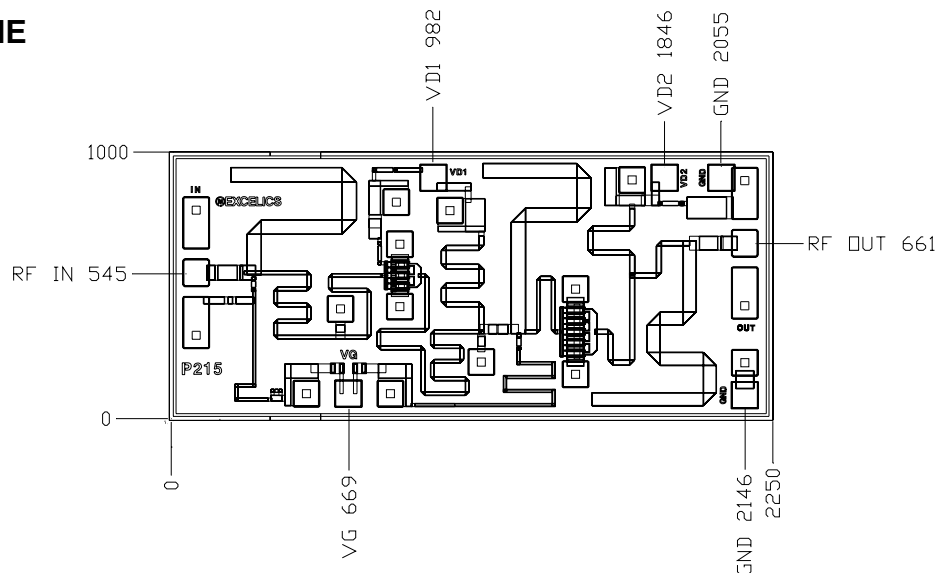
1. Operating the device beyond any of the above rating may result in permanent damage.
2. Bias conditions must also satisfy the following equation $V_{DS} \cdot I_{DS} < (T_{CH} - T_{HS}) / R_{TH}$; where T_{HS} = ambient temperature

ASSEMBLY DRAWING



The length of RF wires should be as short as possible. Use at least two wires between RF pad and 50 ohm line and separate the wires to minimize the mutual inductance.

CHIP OUTLINE



Specifications are subject to change without notice.



EMP215

UPDATED 05/08/2008

12.5 – 16.5 GHz Power Amplifier MMIC

DISCLAIMER

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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